

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Woo Chul JEON	06/10/2010
Ki Yeol PARK	06/10/2010
Young Hwan PARK	06/10/2010
Jung Hee LEE	06/14/2010

RECEIVING PARTY DATA

Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.
Street Address:	314 Maetan 3-Dong, Yeongtong-Gu
City:	Suwon, Gyunggi-Do
State/Country:	KOREA, DEMOCRATIC PEOPLE'S REPUBLIC OF
Postal Code:	443-743

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12842303

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	085946-0156
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NAME OF SUBMITTER:	Stephen A. Becker
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Total Attachments: 2
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CH \$40.00 12842303

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**PATENT
 REEL: 024731 FRAME: 0338**

RECORDATION FORM COVER SHEET

Docket No.: 085946-0156

PATENTS ONLY

To the Director of the U. S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of Conveying Party(ies)
 Woo Chul JEON, Ki Yeol PARK, Young Hwan PARK, Jung Hee LEE

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of Conveyance/Execution Date(s)

Execution Date(s): **June 10, 2010, June 10, 2010, June 10, 2010 and June 14, 2010 (respectively)**

Assignment Merger
 Security Agreement Change of Name
 Joint Research Agreement
 Government Interest Assignment
 Executive Order 9424, Confirmatory License
 Other

2. Name and address of receiving party(ies)
 Name: **SAMSUNG ELECTRO-MECHANICS CO., LTD.**

Internal Address:

Address: **314 Maetan 3-Dong, Yeongtong-Gu, Suwon, Gyeonggi-Do, REPUBLIC OF KOREA 443-743**

Additional name(s) & address(es) attached? Yes No

4. Application or patent number(s):
 A. Patent Application No(s).
 Additional numbers attached? Yes No

This document is being filed together with a new application.
 B. Patent No(s).

5. Name and address to whom correspondence concerning document should be mailed:

Name: **MCDERMOTT WILL & EMERY LLP**
 Internal Address:
 Street Address: **600 13th Street, N.W.**
 City: **Washington, DC** Zip: **20005-3096**
 D.C.
 Phone Number: **202.756.8000**
 Fax Number: **202.756.8087**
 Email Address:

6. Total number of applications and patents involved: **1**

7. Total fee (37 CFR 1.21(h) & 3.41) **\$40.00**

Authorized to be charged by credit card
 Authorized to be charged to deposit account
 Enclosed
 None required (government interest not affecting title)

8. Payment Information:

a. Credit Card Last 4 Numbers _____
 Expiration Date _____

b. Deposit Account Number **500417**
 Authorized User Name _____

9. Signature. *Stephen A. Becker* Reg. No. **51,321**
 X- **Stephen A. Becker 26,527** **July 23, 2010**

Name and Registration No. of Person Signing	Signature	Date
Total number of pages including cover sheet, attachments and documents:		2

(SAB)

Docket No.: _____

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- (1) JEON, Woo Chul
- (2) PARK, Ki Yeol
- (3) PARK, Young Hwan
- (4) LEE, Jung Hee

who have made a certain new and useful invention, hereby sell, assign and transfer unto

SAMSUNG Electro-Mechanics Co., Ltd.
314 Maetan 3-Dong, Yeongtong-Gu,
Suwon, Gyunggi-Do
Republic of KOREA
Postal Code: 443-743

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

NITRIDE BASED SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING OF THE SAME


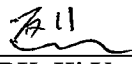


(a) for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS	DATE SIGNED
1) <u></u> Name: JEON, Woo Chul	<u>06/10/2010</u>
2) <u></u> Name: PARK, Ki Yeol	<u>06/10/2010</u>
3) <u></u> Name: PARK, Young Hwan	<u>06/10/2010</u>
4) <u>✓ </u> Name: LEE, Jung Hee	<u>✓ 14/06/2010</u>